MEPTEC2018

HOSTED BY NEXTFLEX

NEW GENERATION FLEXIBLE HYBRID ELECTRONICS

Cost-effective Assembly & Packaging Technologies

AGENDA

7:30 am	**Registration opens – Continental Breakfast will be Served**
8:30 am – 8:45 am	**Welcome and Introduction**
8:45 am – 9:30 am	**KEYNOTE: Flexible Hybrid Electronics – Disrupting Conventional IC Packaging and System Design Solutions** *Wilfried Bair, Senior Engineering Manager, Device Integration and Packaging, NextFlex*
9:30 am – 10:00 am	**The Rationale and Requirements for Pervasive Computing** *Jayna Sheats, CEO, Terecircuit*
10:00 am – 10:30 am	**Advanced Low Dielectric Constant Materials: Learning and Perspectives** *Dr. Geraud DuBois, Head of Data Driven Science to Solutions Organization, Principal Research Staff Member, IBM Research / Adjunct Professor, Stanford University*
10:30 am – 10:45 am	**Break**
10:45 am – 11:15 am	**Process Design Kit (PDK) for Flexible Hybrid Electronics** *Dr. Tsung-Ching "Jim" Huang, Senior Research Scientist, Hewlett-Packard Labs (HPE Labs)*
11:15 am – 11:45 am	**PDK Meets Materials & Process Database** *Jason Marsh, Directory of Technology, NextFlex*
11:45 am – 12:45 pm	**Lunch**
12:45 pm – 1:30 pm	**KEYNOTE: An Alternative History of the Electronics Manufacturing Industry** *Joseph (Joe) Fjelstad, Founder & President, Verdant Electronics*
1:30 pm – 2:00 pm	**Emerging Challenges of Power/Reliability Analysis for FHE** *Dr. Norman Chang, Chief Technologist, Semiconductor Business Unit, ANSYS, Inc., Co-Founder of Apache Design*
2:00 pm – 2:30 pm	**Improving Health Through Continuous Blood Pressure Monitoring** *Dr. Xina Quan, Co-Founder and CTO, PyrAmes (a Stanford University spin-out)*
2:30 pm – 2:45 pm	**Break**
2:45 pm – 3:15 pm	**The Hidden Cost of Ground in Hybrid Electronic Interconnects** *Heidi Barnes, Senior Applications Engineer, Keysight Technologies*
3:15 pm – 3:45 pm	**Materials Development for Flexible Systems and Next Generation Electronics Applications** *Chris Milasincic, New Business Development and Corporate Plans, DowDuPont Electronic Materials Division*
3:45 pm – 4:00 pm	Wrap up
4:00 pm – 4:30 pm	**NextFlex Manufacturing Tour**

Schedule Subject to Change

There will be brief Sponsor Introductions after each presentation.

- ANSYS, Inc.
- ConnecTEC Japan/America
- Gel-Pak
- NAMICS Corporation
- Promex Industries
- SMART Microsystems Ltd.
- SoftMEMS LLC
- Universal Instruments Corporation

THURSDAY, APRIL 26, 2018 | NEXTFLEX FACILITY | SAN JOSE, CALIFORNIA